

CD74HC4051-Q1 ANALOG MULTIPLEXER/DEMULTIPLEXER

SCLS552A – DECEMBER 2003 – REVISED APRIL 2008

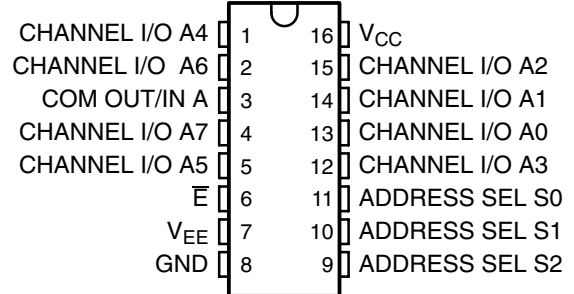
- **Qualified for Automotive Applications**
- **Wide Analog Input Voltage Range of ± 5 V Max**
- **Low ON Resistance**
 - 70 Ω Typical ($V_{CC} - V_{EE} = 4.5$ V)
 - 40 Ω Typical ($V_{CC} - V_{EE} = 9$ V)
- **Low Crosstalk Between Switches**
- **Fast Switching and Propagation Speeds**
- **Break-Before-Make Switching**
- **Operation Control Voltage = 2 V to 6 V**
- **Switch Voltage = 0 V to 10 V**
- **High Noise Immunity $N_{IL} = 30\%$, $N_{IH} = 30\%$ of V_{CC} , $V_{CC} = 5$ V**

description/ordering information

This device is a digitally controlled analog switch that utilizes silicon-gate CMOS technology to achieve operating speeds similar to LSTTL, with the low power consumption of standard CMOS integrated circuits.

This analog multiplexer/demultiplexer controls analog voltages that may vary across the voltage supply range (i.e., V_{CC} to V_{EE}). These bidirectional switches allow any analog input to be used as an output and vice versa. The switches have low ON resistance and low OFF leakages. In addition, the device has an enable control (\bar{E}) that, when high, disables all switches to their OFF state.

M OR PW PACKAGE
(TOP VIEW)



ORDERING INFORMATION†

T_A	PACKAGE‡		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	SOIC – M	Tape and reel		
–40°C to 125°C	SOIC – M	Tape and reel	CD74HC4051QM96Q1	HC4051Q
	TSSOP – PW	Tape and reel	CD74HC4051QPWRQ1	HJ4051Q

† For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at <http://www.ti.com>.

‡ Package drawings, thermal data, and symbolization are available at <http://www.ti.com/packaging>.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 2008, Texas Instruments Incorporated

CD74HC4051-Q1 ANALOG MULTIPLEXER/DEMULTIPLEXER

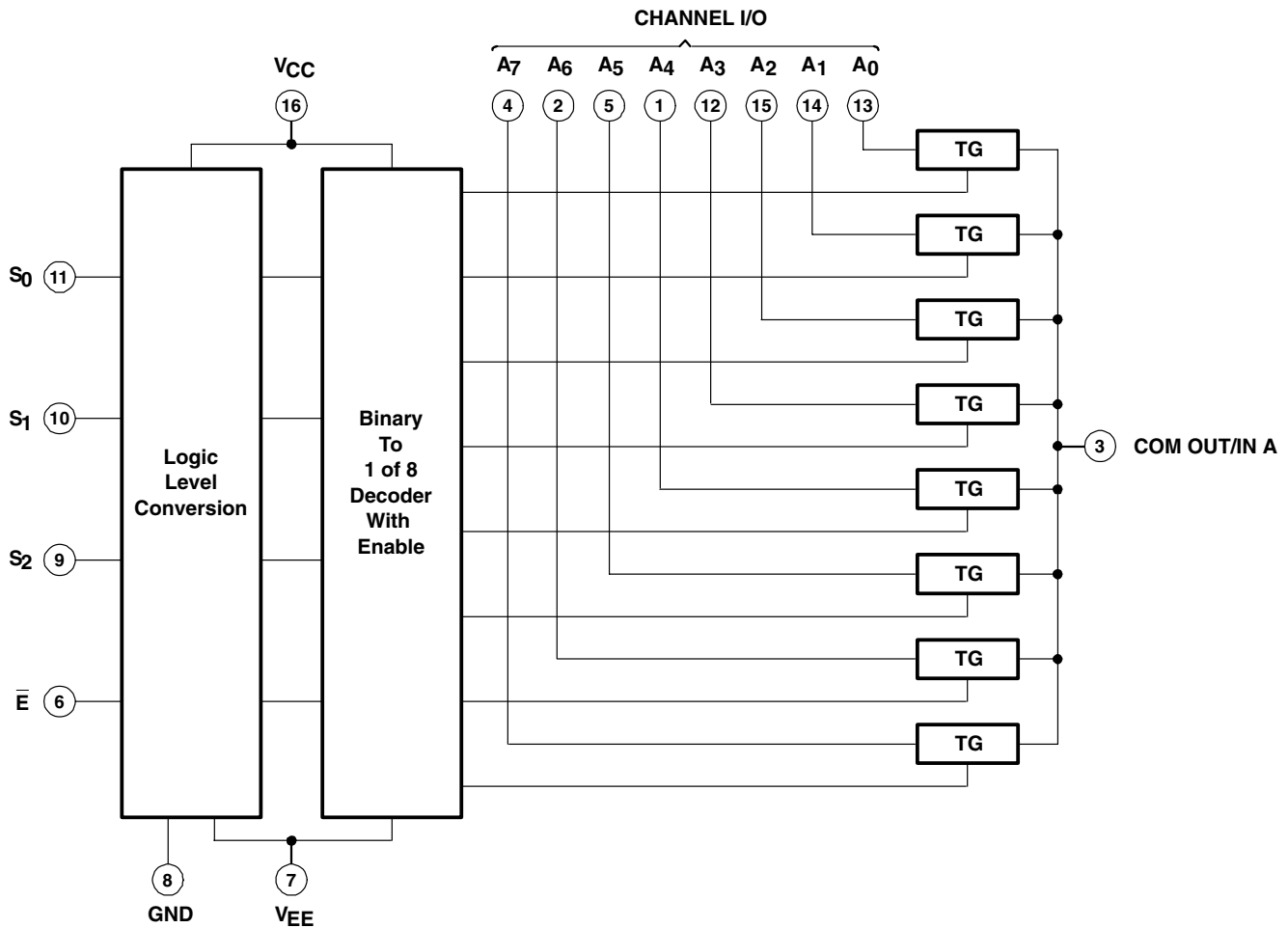
SCLS552A – DECEMBER 2003 – REVISED APRIL 2008

FUNCTION TABLE

INPUTS				ON CHANNEL(S)
E	S ₂	S ₁	S ₀	
L	L	L	L	A0
L	L	L	H	A1
L	L	H	L	A2
L	L	H	H	A3
L	H	L	L	A4
L	H	L	H	A5
L	H	H	L	A6
L	H	H	H	A7
H	X	X	X	None

X = Don't care

logic diagram (positive logic)



CD74HC4051-Q1 ANALOG MULTIPLEXER/DEMULTIPLEXER

SCLS552A – DECEMBER 2003 – REVISED APRIL 2008

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC} - V_{EE}$ (see Note 1)	–0.5 V to 10.5 V
Supply voltage range, V_{CC}	–0.5 V to 7 V
Supply voltage range, V_{EE}	+0.5 V to –7 V
Input clamp current, I_{IK} ($V_I < -0.5$ V or $V_I > V_{CC} + 0.5$ V)	±20 mA
Output clamp current, I_{OK} ($V_O < V_{EE} - 0.5$ V or $V_O > V_{CC} + 0.5$ V)	±20 mA
Switch current ($V_I > V_{EE} - 0.5$ V or $V_I < V_{CC} + 0.5$ V)	±25 mA
Continuous current through V_{CC} or GND	±50 mA
V_{EE} current, I_{EE}	–20 mA
Package thermal impedance, θ_{JA} (see Note 2): M package	73°C/W
PW package	108°C/W
Maximum junction temperature, T_J	150°C
Lead temperature (during soldering):	
At distance $1/16 \pm 1/32$ inch ($1,59 \pm 0,79$ mm) from case for 10 s max	300°C
Storage temperature range, T_{stg}	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltages referenced to GND unless otherwise specified.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT	
V_{CC}	Supply voltage (see Note 4)	2	6	V	
Supply voltage, $V_{CC} - V_{EE}$ (see Figure 1)		2	10	V	
V_{EE}	Supply voltage, (see Note 4 and Figure 2)	0	–6	V	
V_{IH}	High-level input voltage	$V_{CC} = 2$ V	1.5	V	
		$V_{CC} = 4.5$ V	3.15		
		$V_{CC} = 6$ V	4.2		
V_{IL}	Low-level input voltage	$V_{CC} = 2$ V	0.5	V	
		$V_{CC} = 4.5$ V	1.35		
		$V_{CC} = 6$ V	1.8		
V_I	Input control voltage	0	V_{CC}	V	
V_{IS}	Analog switch I/O voltage	V_{EE}	V_{CC}	V	
t_t	Input transition (rise and fall) time	$V_{CC} = 2$ V	0	1000	ns
		$V_{CC} = 4.5$ V	0	500	
		$V_{CC} = 6$ V	0	400	
T_A	Operating free-air temperature	–40	125	°C	

- NOTES: 3. All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.
4. In certain applications, the external load resistor current may include both V_{CC} and signal-line components. To avoid drawing V_{CC} current when switch current flows into the transmission gate inputs, the voltage drop across the bidirectional switch must not exceed 0.6 V (calculated from r_{on} values shown in electrical characteristics table). No V_{CC} current flows through R_L if the switch current flows into the COM OUT/IN A terminal.



CD74HC4051-Q1

ANALOG MULTIPLEXER/DEMULTIPLEXER

SCLS552A – DECEMBER 2003 – REVISED APRIL 2008

recommended operating area as a function of supply voltages

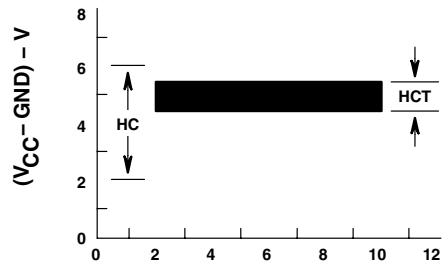


Figure 1

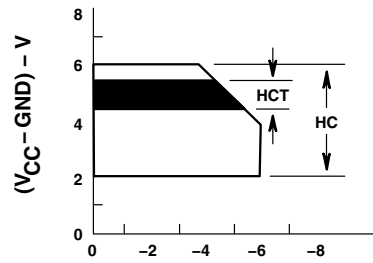


Figure 2

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{EE}	V _{CC}	T _A = 25°C			T _A = -40°C TO 125°C		UNIT	
				MIN	TYP	MAX	MIN	MAX		
r _{on}	I _O = 1 mA, V _I = V _{IH} or V _{IL} , See Figure 8	V _{IS} = V _{CC} or V _{EE}	0 V	4.5 V	70	160	240		Ω	
			0 V	6 V	60	140	210			
			-4.5 V	4.5 V	40	120	180			
		V _{IS} = V _{CC} to V _{EE}	0 V	4.5 V	90	180	270			
			0 V	6 V	80	160	240			
			-4.5 V	4.5 V	45	130	195			
Δr _{on}	Between any two channels	0 V	4.5 V	10					Ω	
		0 V	6 V	8.5						
		-4.5 V	4.5 V	5						
I _{IZ}	For switch OFF: When V _{IS} = V _{CC} , V _{OS} = V _{EE} ; When V _{IS} = V _{EE} , V _{OS} = V _{CC} For switch ON: All applicable combinations of V _{IS} and V _{OS} voltage levels, V _I = V _{IH} or V _{IL}	0 V	6 V	±0.2			±2		μA	
		-5 V	5 V	±0.4			±4			
I _{IL}	V _I = V _{CC} or GND	0 V	6 V	±0.1			±1		μA	
I _{CC}	I _O = 0, V _I = V _{CC} or GND	When V _{IS} = V _{EE} , V _{OS} = V _{CC}	0 V	6 V	8			160		μA
		When V _{IS} = V _{CC} , V _{OS} = V _{EE}	-5 V	5 V	16			320		

CD74HC4051-Q1 ANALOG MULTIPLEXER/DEMULTIPLEXER

SCLS552A – DECEMBER 2003 – REVISED APRIL 2008

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 7)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	V _{EE}	V _{CC}	T _A = 25°C			T _A = -40°C TO 125°C		UNIT
						MIN	TYP	MAX	MIN	MAX	
t _{pd}	IN	OUT	C _L = 15 pF		5 V	4					ns
			C _L = 50 pF	0 V	2 V	60			90		ns
					4.5 V	12			18		
					6 V	10			15		
-4.5 V	4.5 V			8		12					
t _{en}	ADDRESS SEL or \bar{E}	OUT	C _L = 15 pF		5 V	19					ns
			C _L = 50 pF	0 V	2 V	225			340		
					4.5 V	45			68		
					6 V	38			57		
-4.5 V	4.5 V			32		48					
t _{dis}	ADDRESS SEL or \bar{E}	OUT	C _L = 15 pF		5 V	19					ns
			C _L = 50 pF	0 V	2 V	225			340		
					4.5 V	45			68		
					6 V	38			57		
-4.5 V	4.5 V			32		48					
C _I	Control		C _L = 50 pF					10	10	pF	

operating characteristics, V_{CC} = 5 V, T_A = 25°C, Input t_r, t_f = 6 ns

PARAMETER		TYP	UNIT
C _{pd}	Power dissipation capacitance (see Note 5)	50	pF

NOTE 5: C_{pd} is used to determine the dynamic power consumption, per package.

$$P_D = C_{pd} V_{CC}^2 f_i + \sum (C_L + C_S) V_{CC}^2 f_O$$

f_O = output frequency

f_i = input frequency

C_L = output load capacitance

C_S = switch capacitance

V_{CC} = supply voltage

CD74HC4051-Q1

ANALOG MULTIPLEXER/DEMULTIPLEXER

SCLS552A – DECEMBER 2003 – REVISED APRIL 2008

analog channel characteristics, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	V_{EE}	V_{CC}	MIN	TYP	MAX	UNIT
C_I	Switch input capacitance				5		pF
C_{COM}	Common output capacitance				25		pF
f_{max}	Minimum switch frequency response at -3 dB	-2.25 V	2.25 V		145		MHz
		-4.5 V	4.5 V		180		
Sine-wave distortion	See Figure 4	-2.25 V	2.25 V		0.035		%
		-4.5 V	4.5 V		0.018		
\bar{E} or ADDRESS SEL to switch feed-through noise	See Figure 5, and Notes 7 and 8	-2.25 V	2.25 V		(TBD)		mV
		-4.5 V	4.5 V		(TBD)		
Switch OFF signal feed through	See Figure 6 and Figure 10, and Notes 7 and 8	-2.25 V	2.25 V		-73		dB
		-4.5 V	4.5 V		-75		

- NOTES: 6. Adjust input voltage to obtain 0 dBm at V_{OS} for $f_{IN} = 1$ MHz.
 7. V_{IS} is centered at $(V_{CC} - V_{EE})/2$.
 8. Adjust input for 0 dBm.

PARAMETER MEASUREMENT INFORMATION

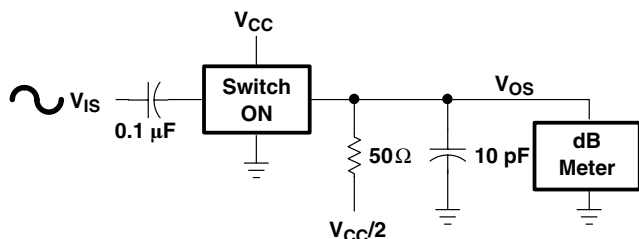


Figure 3. Frequency-Response Test Circuit

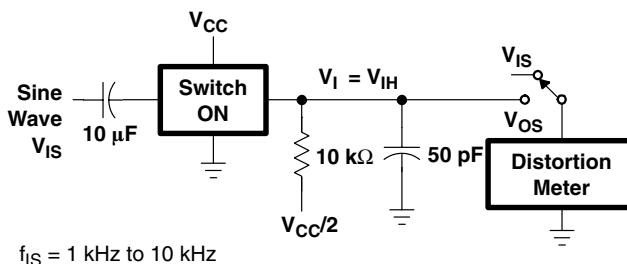


Figure 4. Sine-Wave Distortion Test Circuit

PARAMETER MEASUREMENT INFORMATION

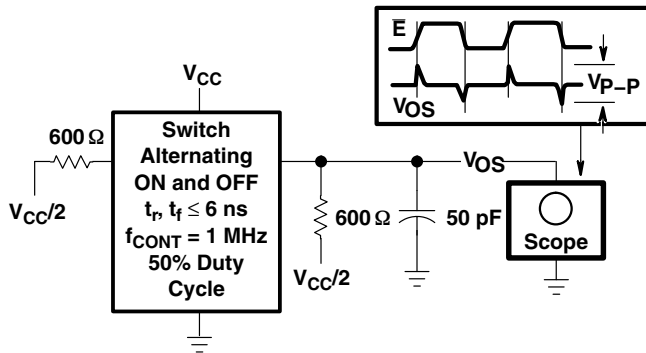


Figure 5. Control to Switch Feedthrough Noise Test Circuit

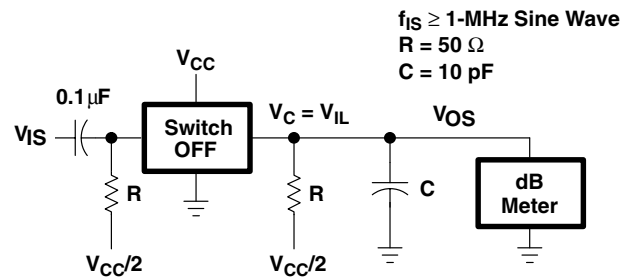
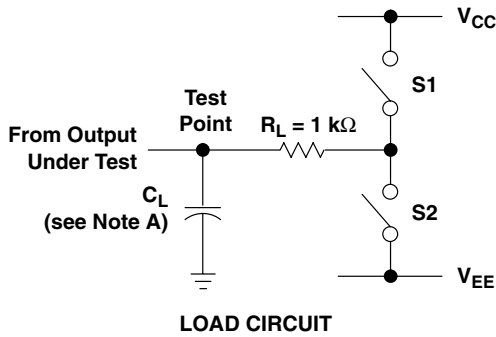


Figure 6. Switch OFF Signal Feedthrough Test Circuit

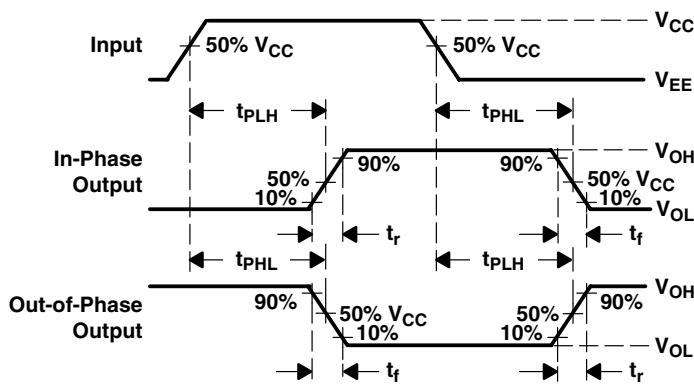
CD74HC4051-Q1 ANALOG MULTIPLEXER/DEMULTIPLEXER

SCLS552A – DECEMBER 2003 – REVISED APRIL 2008

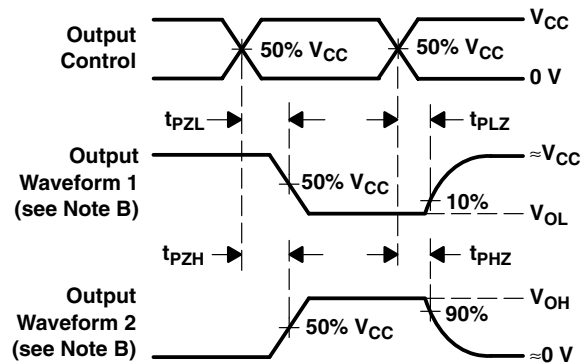
PARAMETER MEASUREMENT INFORMATION



PARAMETER		S1	S2
t_{en}	t_{pZH}	Open	Closed
	t_{pZL}	Closed	Open
t_{dis}	t_{pHZ}	Open	Closed
	t_{pLZ}	Closed	Open
t_{pd}		Open	Open



**VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES**



**VOLTAGE WAVEFORMS
OUTPUT ENABLE AND DISABLE TIMES**

- NOTES: A. C_L includes probe and test-fixtue capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1$ MHz, $Z_O = 50 \Omega$, $t_r = 6$ ns, $t_f = 6$ ns.
 D. For clock inputs, f_{max} is measured with the input duty cycle at 50%.
 E. The outputs are measured one at a time with one input transition per measurement.
 F. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 G. t_{PZL} and t_{PZH} are the same as t_{en} .
 H. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 7. Load Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS

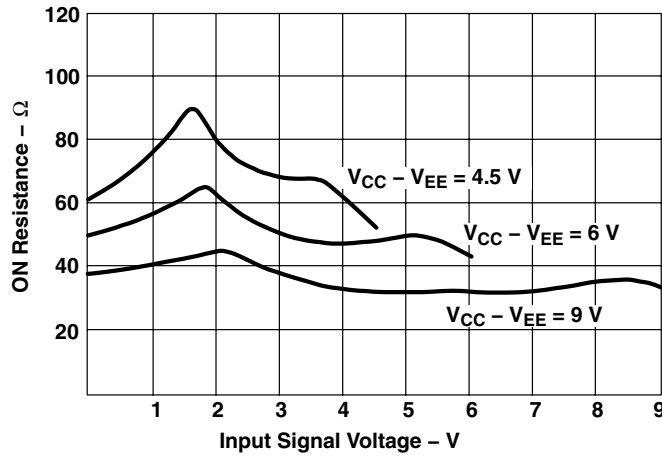


Figure 8. Typical ON Resistance vs Input Signal Voltage

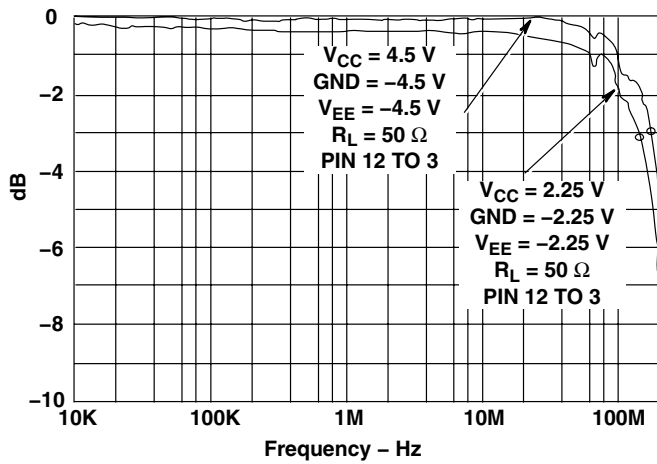


Figure 9. Channel ON Bandwidth

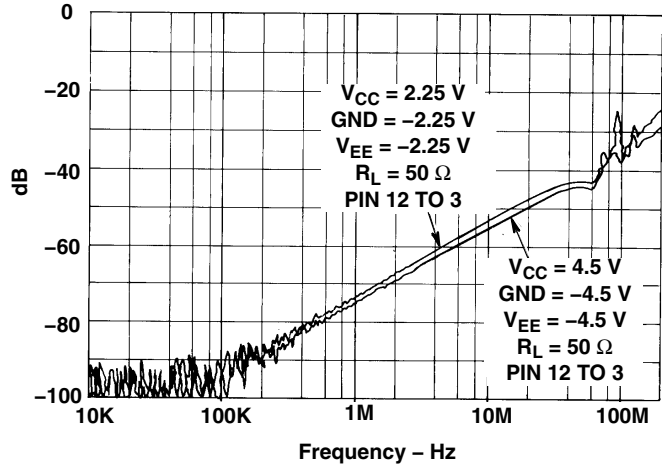


Figure 10. Channel OFF Feedthrough

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
CD74HC4051QM96G4Q1	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC4051QM96Q1	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC4051QPWRG4Q1	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC4051QPWRQ1	ACTIVE	TSSOP	PW	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF CD74HC4051-Q1 :

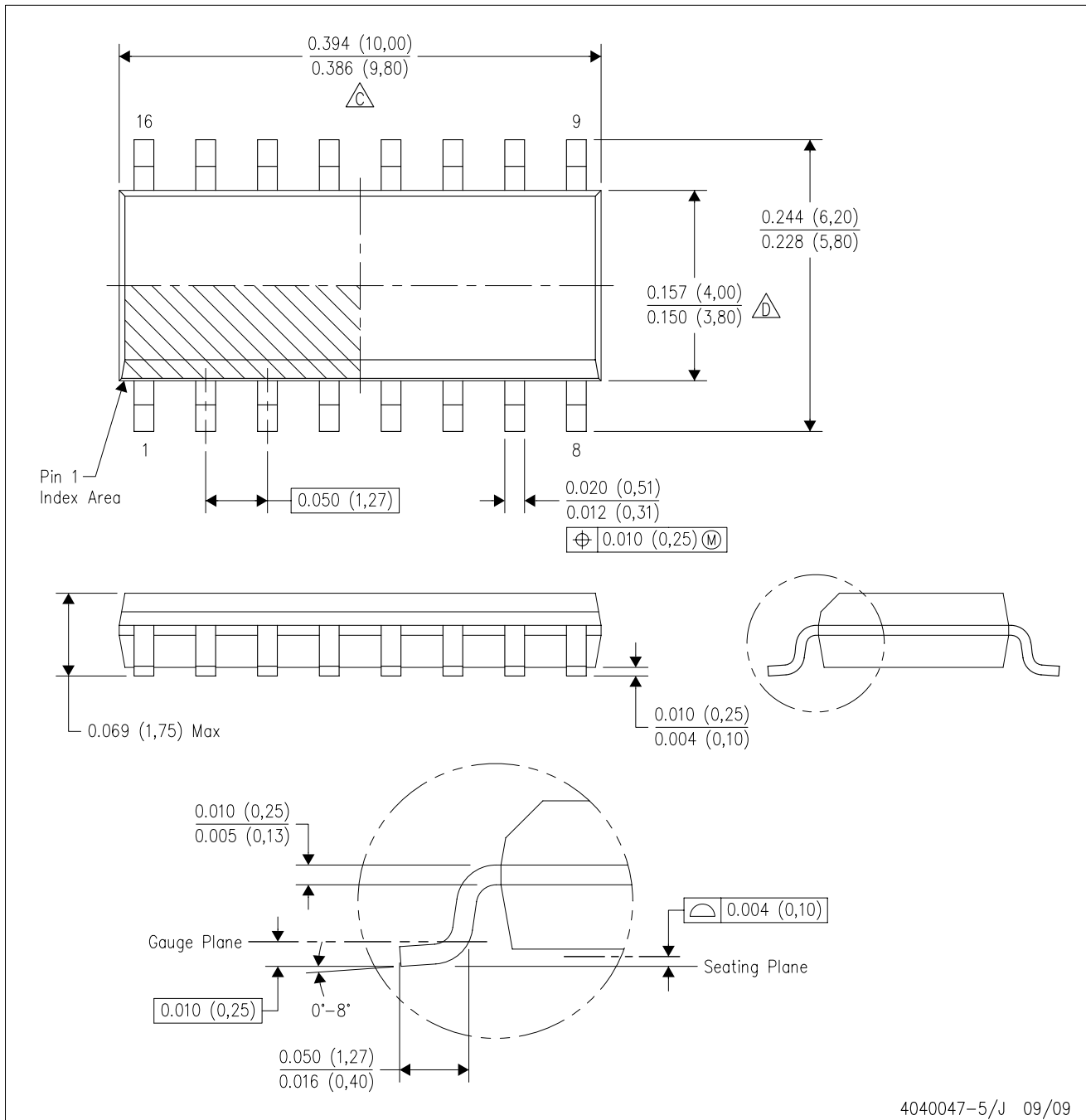
- Catalog: [CD74HC4051](#)
- Enhanced Product: [CD74HC4051-EP](#)
- Military: [CD54HC4051](#)



NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications

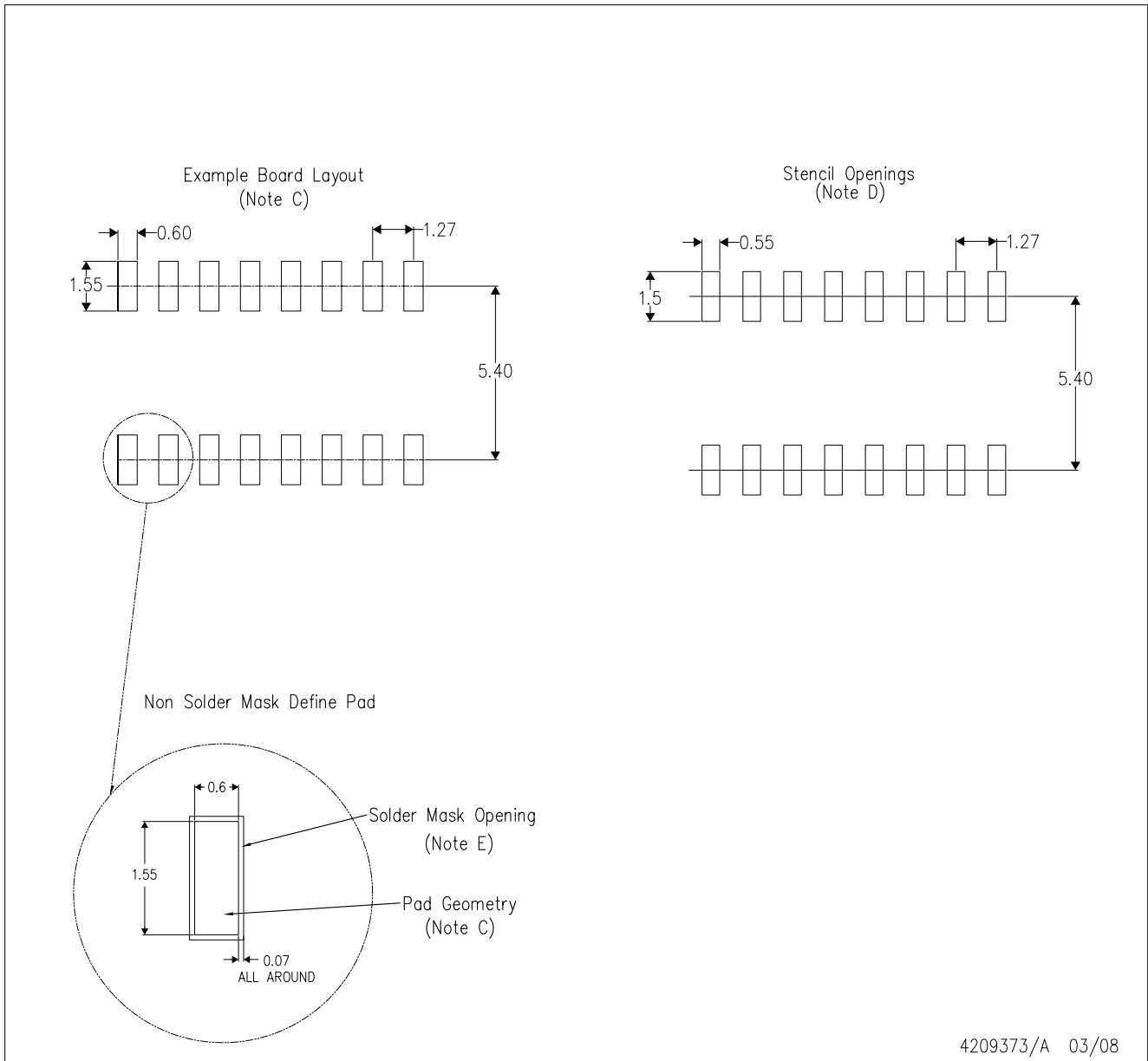
D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 -  D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AC.

D(R-PDSO-G16)



4209373/A 03/08

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Refer to IPC7351 for alternate board design.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DLP® Products	www.dlp.com	Communications and Telecom	www.ti.com/communications
DSP	dsp.ti.com	Computers and Peripherals	www.ti.com/computers
Clocks and Timers	www.ti.com/clocks	Consumer Electronics	www.ti.com/consumer-apps
Interface	interface.ti.com	Energy	www.ti.com/energy
Logic	logic.ti.com	Industrial	www.ti.com/industrial
Power Mgmt	power.ti.com	Medical	www.ti.com/medical
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
RFID	www.ti-rfid.com	Space, Avionics & Defense	www.ti.com/space-avionics-defense
RF/IF and ZigBee® Solutions	www.ti.com/lprf	Video and Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless-apps